



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2019-01-18
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T3035H-6I	7BVT*306SBT1	A	3068	2019-01-18
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10 - 15.5 - 4.5	3	Through-hole	
Comment	TO 220 I CLIP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
10a	Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound. This exemption does not cover the use of lead in: — glass in bulbs and glaze of spark plugs — dielectric ceramic materials of components listed under

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	4.22	Die - Leadframe	2221
Lead	27.47	Soft solder - solder paste	14458
Lead-Borate Glass	3.19	Die	1678

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	27.47	Soft solder - Solder paste	14458
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	13.40	Soft solder	920261
Lead	1000 ppm	14.07	Solder paste	849964

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7BVT*306SBT1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	18.611	mg	supplier	die	Silicon (Si)	7440-21-3		14.545	mg	781527	7655
				supplier	metallization	Gold (Au)	7440-57-5		0.055	mg	2955	29
				supplier	passivation	Nickel (Ni)	7440-02-0		0.292	mg	15690	154
				supplier	Passivation	Silicon Oxide	7631-86-9		0.117	mg	6287	62
				supplier	back side metallization	Gold (Au)	7440-57-5		0.019	mg	1020	10
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.395	mg	21224	208
Leadframe	M-004 Copper and its alloys	1593.079	mg	JIG-R & California 65	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	3.188	mg	171297	1678
				supplier	alloy	Copper (Cu)	7440-50-8		1587.709	mg	996629	835636
				supplier	alloy	Iron (Fe)	7439-89-6		0.731	mg	459	385
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.335	mg	838	703
				supplier	metallization	Nickel (Ni)	7440-02-0		3.304	mg	2074	1739
Soft solder	Solder	14.560	mg	SVHC	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	13.399	mg	920261	7052
				supplier	solder	Silver (Ag)	7440-22-4		0.363	mg	24931	191
				supplier	solder	Tin (Sn)	7440-31-5		0.725	mg	49794	382
				supplier	solder	flux residue	Proprietary		0.073	mg	5014	38
Clip	M-004 Copper and its alloys	31.625	mg	supplier	clip	Copper (Cu)	7440-50-8		31.625	mg	1000000	16645
Encapsulation	M-011 Other inorganic materials	196.497	mg	supplier	mold compound	Silica, vitreous	60676-86-0		149.337	mg	759996	78598
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		20.043	mg	102002	10549
				supplier	mold compound	Phenol resin	9003-35-4		11.790	mg	60001	6205
				supplier	mold compound	Others	Proprietary		9.825	mg	50001	5171
				supplier	mold compound	Metal hydroxide	21645-51-2		3.930	mg	20000	2068
				supplier	mold compound	Carbon black	1333-86-4		1.572	mg	8000	827
Solder paste	Solder	16.556	mg	SVHC	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	14.072	mg	849964	7406
				supplier	solder	Antimony (Sb)	7440-36-0		1.656	mg	100024	872
				supplier	solder	Tin (Sn)	7440-31-5		0.828	mg	50012	436
Connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	3323
Ceramic	M-010 Ceramics / glass	22.758	mg	supplier	ceramic	Alumina	1344-28-1		22.530	mg	989982	11858
				supplier	metallization	Nickel (Ni)	7440-02-0		0.228	mg	10018	120